N-Channel Enhancement-Mode Vertical DMOS FETs

Ordering Information

BV_{DSS} / BV_{DGS}	$R_{DS(ON)}$ (max)	Order Number / Package		
		TO-92	TO-236AB*	Die†
60V	4.0Ω	VN2106N3	–	VN2106ND
100V	4.0Ω	—	VN2110K1	VN2110ND

†MIL visual screening available
*Same as SOT-23. All units shipped on 3,000 piece carrier tape reels.

Product marking for SOT-23:
N1A*
where * = 2-week alpha date code

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Features

- Commercial and Military versions available
- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- Low C_{ISS} and fast switching speeds
- High input impedance and high gain

Applications

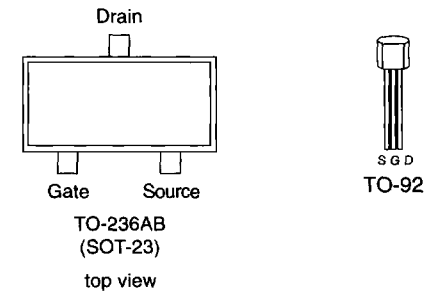
- Motor controls
- Amplifiers
- Power supply circuits
- Converters
- Switches
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

Advanced DMOS Technology

These enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options



Note: See Package Outline section for dimensions.

Thermal Characteristics

Package	I_D (continuous)†	I_D (pulsed)	Power Dissipation* @ T_C = 25°C	θ_{jc} °C/W	θ_{ja} °C/W	I_{DR}†	I_{DRM}
TO-92	0.25A	1.0A	1.0W	125	170	0.25A	1.0A
TO-236AB	0.2A	0.8A	0.36W (T_A = 25°C)	200	350	0.2A	0.8A

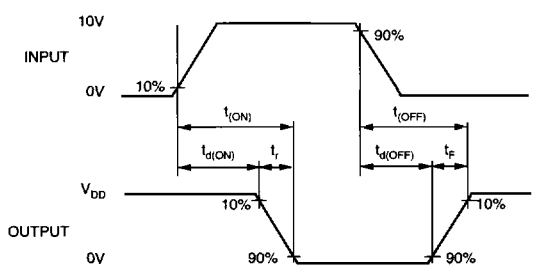
† I_D (continuous) is limited by max rated T_j.
* Total for package.

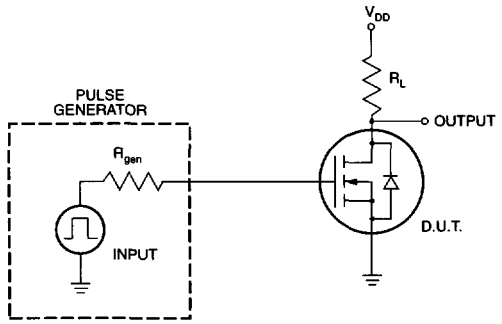
Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter		Min	Typ	Max	Unit	Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	VN2110	100			V	I_D = 1mA, V_{GS} = 0V
		VN2106	60				
$V_{GS(th)}$	Gate Threshold Voltage		0.8		2.4	V	V_{GS} = V_{DS}, I_D = 1mA
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with Temperature			-3.8	-5.5	mV/°C	V_{GS} = V_{DS}, I_D = 1mA
I_{GSS}	Gate Body Leakage			0.1	100	nA	V_{GS} = ±20V, V_{DS} = 0V
I_{DSS}	Zero Gate Voltage Drain Current				1	µA	V_{GS} = 0V, V_{DS} = Max Rating
					100	µA	V_{GS} = 0V, V_{DS} = 0.8 Max Rating, T_A = 125°C
$I_{D(ON)}$	ON-State Drain Current		0.6			A	V_{GS} = 10V, V_{DS} = 25V
$R_{DS(ON)}$	Static Drain-to-Source ON-State Resistance			4.5	6.0	Ω	V_{GS} = 5V, I_D = 75mA
				3.0	4.0	Ω	V_{GS} = 10V, I_D = 500mA
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with Temperature			0.70	1.0	%/°C	V_{GS} = 10V, I_D = 500mA
G_{FS}	Forward Transconductance		150	400		m℧	V_{DS} = 25V, I_D =0.5A
C_{ISS}	Input Capacitance			35	50	pF	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz
C_{OSS}	Common Source Output Capacitance			13	25		
C_{RSS}	Reverse Transfer Capacitance			4	5		
$t_{d(ON)}$	Turn-ON Delay Time			3	5	ns	V_{DD} = 25V, I_D = 0.6A, R_{GEN} = 25Ω
t_r	Rise Time			5	8		
$t_{d(OFF)}$	Turn-OFF Delay Time			6	9		
t_f	Fall Time			5	8		
V_{SD}	Diode Forward Voltage Drop			1.2	1.8	V	I_{SD} = 0.6A, V_{GS} = 0V
t_{rr}	Reverse Recovery Time			400		ns	I_{SD} = 0.6A, V_{GS} = 0V

Notes:
1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

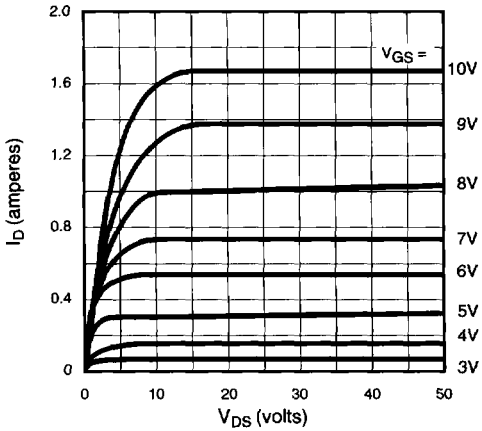
Switching Waveforms and Test Circuit



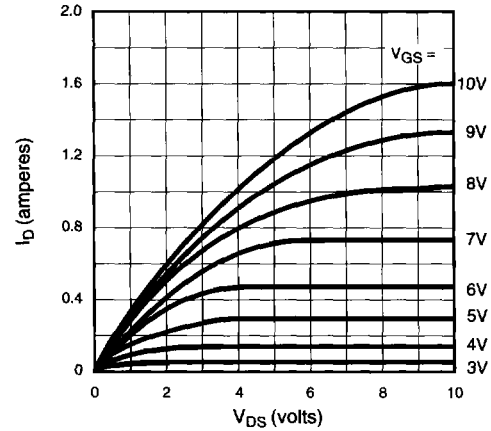


Typical Performance Curves

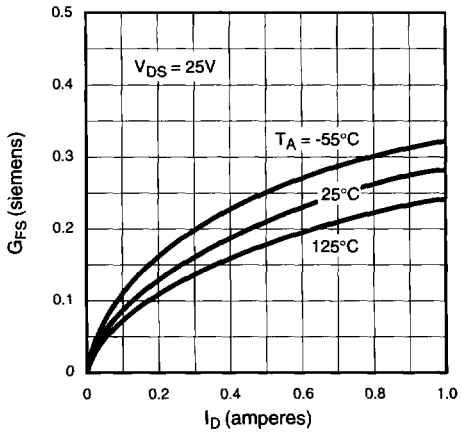
Output Characteristics



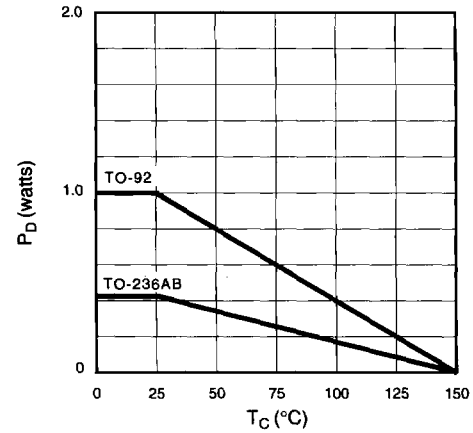
Saturation Characteristics



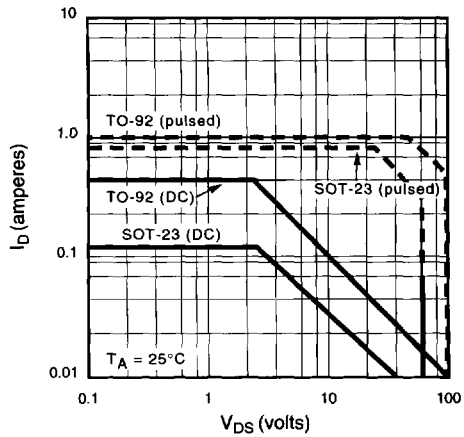
Transconductance vs. Drain Current



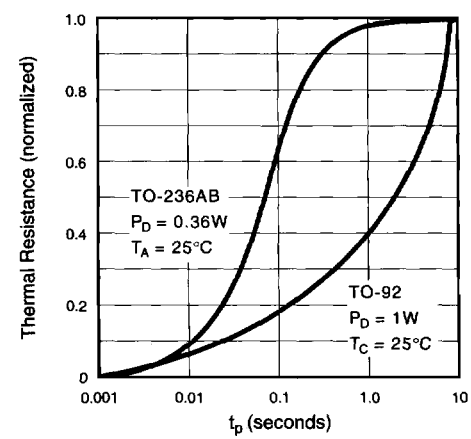
Power Dissipation vs. Case Temperature



Maximum Rated Safe Operating Area



Thermal Response Characteristics



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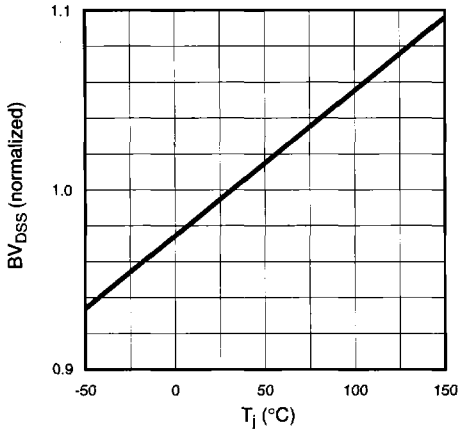
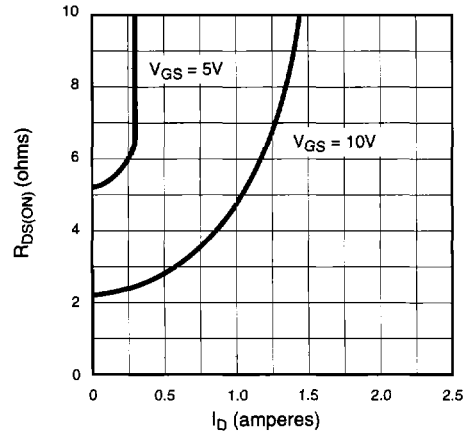
Typical Performance Curves

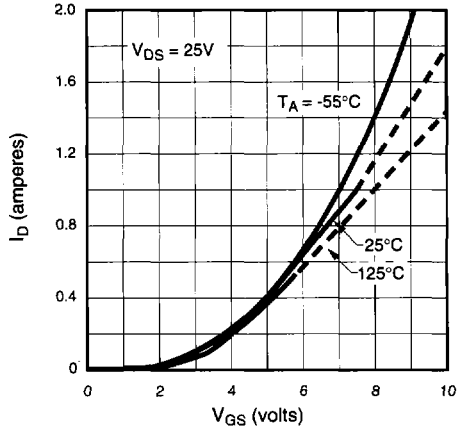
BV$_{DSS}$ Variation with Temperature



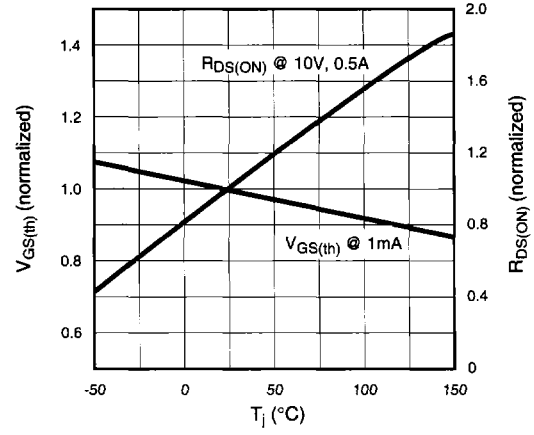
On-Resistance vs. Drain Current



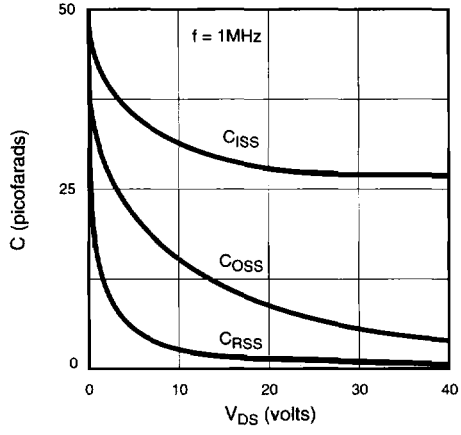
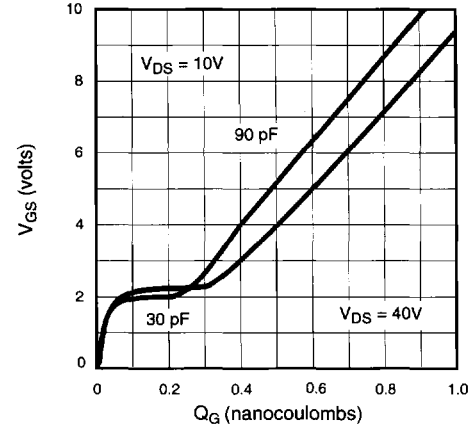
Transfer Characteristics



VGS(th) and RDS(ON) Variation with Temperature



Capacitance vs. Drain-to-Source Voltage



Gate Drive Dynamic Characteristics